

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3234	((438/622) or (438/641) or (438/644)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/11 10:59
L2	18	(binder near free) and CTE	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/11 10:59
L3	0	1 and L2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/11 10:59
S2	3388	(filler near material) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 18:52
S3	306	S2 and CTE	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 18:20
S4	96	S3 and ((copper or gold or silver) same filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 18:52
S5	77	((filler near material) same CTE) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 18:52
S6	33	S5 and ((copper or gold or silver) same filler)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 18:52
S7	2	("5496755").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/08 11:09

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S8	13	((("5696002") or ("5773352") or ("5946584") or ("6096574") or ("6097091") or ("6110825") or ("6114221") or ("6225651") or ("6259153") or ("6294837") or ("6300670") or ("6303469") or ("6319751"))).PN.	USPAT	OR	OFF	2005/07/08 11:29
S9	1659	(semiconductor near substrate) with (via near hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/08 11:17
S10	0	((semiconductor near substrate) with (via near hole)) same (filler and CTE)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/08 11:18
S11	1	((semiconductor near substrate) with (via near hole)) same filler	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/08 11:22
S12	15	((semiconductor near substrate) with (via near hole)) and CTE	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/08 11:23
S13	7	((("3752685") or ("5337475") or ("5614043") or ("6143421") or ("6329065") or ("6346317") or ("6426126"))).PN.	USPAT	OR	OFF	2005/07/08 14:38
S15	4633	CTE and via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/04 16:25
S16	567	CTE and ((via or vias) near (hole or holes))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/04 16:26
S17	514	S16 and (copper or Cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/04 16:26

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S18	424	S17 not (@ad>"20031203" or @riad>"20031203")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/04 16:35
S19	198	S18 and vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/04 16:35
S20	215	toledo.xa.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/04 18:31
S21	1	(binder near free) same (filler near material)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/12 17:12
S22	16	(binder near free) and CTE	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/17 10:27
S23	2	(binder near free) and sinter\$3 and (filler near material) and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/17 10:33
S24	5	(binder near free) same paste and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/17 10:34